

## SN74AHCT1G32 Single 2-Input Positive-OR Gate

### 1 Features

- Operating range of 4.5V to 5.5V
- Max  $t_{pd}$  of 8ns at 5V
- Low power consumption, 10 $\mu$ A max  $I_{CC}$
- $\pm 8$ mA output drive at 5V
- Inputs are TTL-voltage compatible
- Latch-up performance exceeds 250mA per JESD 17

### 2 Applications

- I/O Modules; Analog PLC/DCS Inputs
- Server Motherboards
- Automotive Clusters
- Motor Drives and Controls
- DLP Front Projection Systems
- TVs
- Set-top-boxes
- Audio

### 3 Description

The SN74AHCT1G32 device is a single 2-input positive-OR gate. The device performs the Boolean function  $Y = A + B$  or  $Y = \overline{A} \cdot \overline{B}$  in positive logic.

**Table 3-1. Package Information**

PART NUMBER	PACKAGE <sup>(1)</sup>	PACKAGE SIZE <sup>(2)</sup>	BODY SIZE <sup>(3)</sup>
SN74AHCT1G32	DBV (SOT-23, 5)	2.90mm x 2.8mm	2.90mm x 1.60mm
	DCK (SC-70, 5)	2.00mm x 2.1mm	2.00mm x 1.30mm
	DRL (SOT-553, 5)	1.65mm x 1.6mm	1.65mm x 1.20mm

- (1) For more information, see [Section 11](#).
- (2) The package size (length  $\times$  width) is a nominal value and includes pins, where applicable.
- (3) The body size (length  $\times$  width) is a nominal value and does not include pins.



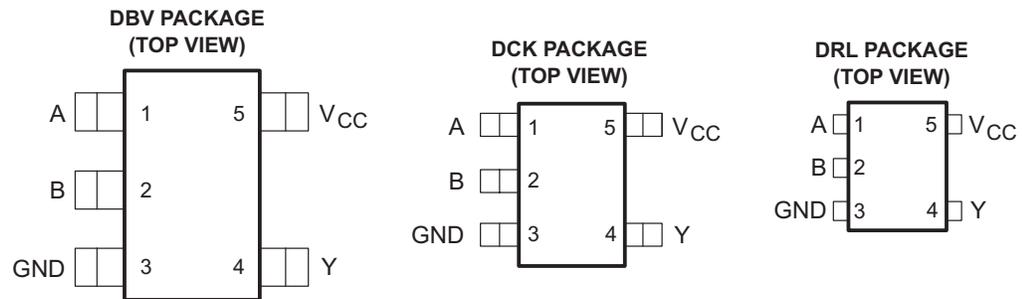
**Simplified Schematic**



## Table of Contents

<b>1 Features</b> .....	1	7.3 Feature Description.....	8
<b>2 Applications</b> .....	1	7.4 Device Functional Modes.....	8
<b>3 Description</b> .....	1	<b>8 Application and Implementation</b> .....	9
<b>4 Pin Configuration and Functions</b> .....	3	8.1 Application Information.....	9
<b>5 Specifications</b> .....	4	8.2 Typical Application.....	9
5.1 Absolute Maximum Ratings.....	4	8.3 Power Supply Recommendations.....	10
5.2 ESD Ratings.....	4	8.4 Layout.....	10
5.3 Recommended Operating Conditions.....	4	<b>9 Device and Documentation Support</b> .....	11
5.4 Thermal Information.....	5	9.1 Receiving Notification of Documentation Updates....	11
5.5 Electrical Characteristics.....	5	9.2 Support Resources.....	11
5.6 Switching Characteristics.....	5	9.3 Trademarks.....	11
5.7 Operating Characteristics.....	5	9.4 Electrostatic Discharge Caution.....	11
5.8 Typical Characteristics.....	6	9.5 Glossary.....	11
<b>6 Parameter Measurement Information</b> .....	7	<b>10 Revision History</b> .....	11
<b>7 Detailed Description</b> .....	8	<b>11 Mechanical, Packaging, and Orderable Information</b> .....	11
7.1 Overview.....	8		
7.2 Functional Block Diagram.....	8		

## 4 Pin Configuration and Functions



See mechanical drawings for dimensions.

**Table 4-1. Pin Functions**

PIN		TYPE <sup>(1)</sup>	DESCRIPTION
NO.	NAME		
1	A	I	Input A
2	B	I	Input B
3	GND	—	Ground Pin
4	Y	O	Output Y
5	V <sub>CC</sub>	—	Power Pin

(1) Signal Types: I = Input, O = Output, I/O = Input or Output

## 5 Specifications

### 5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range	-0.5	7	V
V <sub>I</sub>	Input voltage range <sup>(2)</sup>	-0.5	7	V
V <sub>O</sub>	Output voltage range <sup>(2)</sup>	-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0	-20	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub>	±20	mA
I <sub>O</sub>	Continuous output current	V <sub>O</sub> = 0 to V <sub>CC</sub>	±25	mA
	Continuous current through V <sub>CC</sub> or GND		±50	mA
T <sub>stg</sub>	Storage temperature range	-65	150	°C
T <sub>J</sub>	Junction Temperature		150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under [Section 5.3](#) is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

### 5.2 ESD Ratings

		VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge		
	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>	±2000	V
	Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>	±1000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	4.5	5.5	V
V <sub>IH</sub>	High-level input voltage	2		V
V <sub>IL</sub>	Low-level input voltage		0.8	V
V <sub>I</sub>	Input voltage	0	5.5	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current		-8	mA
I <sub>OL</sub>	Low-level output current		8	mA
Δt/Δv	Input transition rise or fall rate		20	ns/V
T <sub>A</sub>	Operating free-air temperature	-40	125	°C

- (1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs* ([SCBA004](#)).

## 5.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		SN74AHCT1G32			UNIT
		DBV	DCK	DRL	
		5 PINS			
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	278	287.6	328.7	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	180.5	97.7	105.1	
R <sub>θJB</sub>	Junction-to-board thermal resistance	184.4	65.	150.3	
ψ <sub>JT</sub>	Junction-to-top characterization parameter	115.4	2.0	6.9	
ψ <sub>JB</sub>	Junction-to-board characterization parameter	183.4	64.2	148.4	
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	N/A	N/A	N/A	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report (SPRA953).

## 5.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			–40°C to 85°C		–40°C to 125°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	High level output voltage I <sub>OH</sub> = –50 μA	4.5 V	4.4	4.5		4.4		4.4	V	
			3.94			3.8		3.8		
V <sub>OL</sub>	Low level output voltage I <sub>OL</sub> = 50 μA	4.5 V			0.1		0.1	0.1	V	
					0.36		0.44	0.44		
I <sub>I</sub>	Input leakage current V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V			±0.1		±1	±1	μA	
I <sub>CC</sub>	Supply current V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V			1		10	10	μA	
ΔI <sub>CC</sub> <sup>(1)</sup>	Supply-current change One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	5.5 V			1.35		1.5	1.5	mA	
C <sub>i</sub>	Input Capacitance V <sub>I</sub> = V <sub>CC</sub> or GND	5 V			2	10		10	pF	

(1) This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.

## 5.6 Switching Characteristics

over recommended operating free-air temperature range, V<sub>CC</sub> = 5 V ± 0.5 V (unless otherwise noted) (see Figure 6-1)

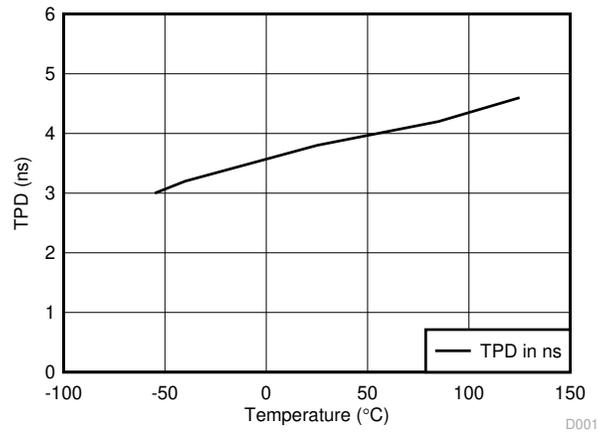
PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T <sub>A</sub> = 25°C			–40°C to 85°C		–40°C to 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	Y	C <sub>L</sub> = 15 pF	5	6.9		1	8	1	9	ns
t <sub>PHL</sub>				5	6.9		1	8	1	9	
t <sub>PLH</sub>	A or B	Y	C <sub>L</sub> = 50 pF	5.5	7.9		1	9	1	10	ns
t <sub>PHL</sub>				5.5	7.9		1	9	1	10	

## 5.7 Operating Characteristics

V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	No load, f = 1 MHz	11.5	pF

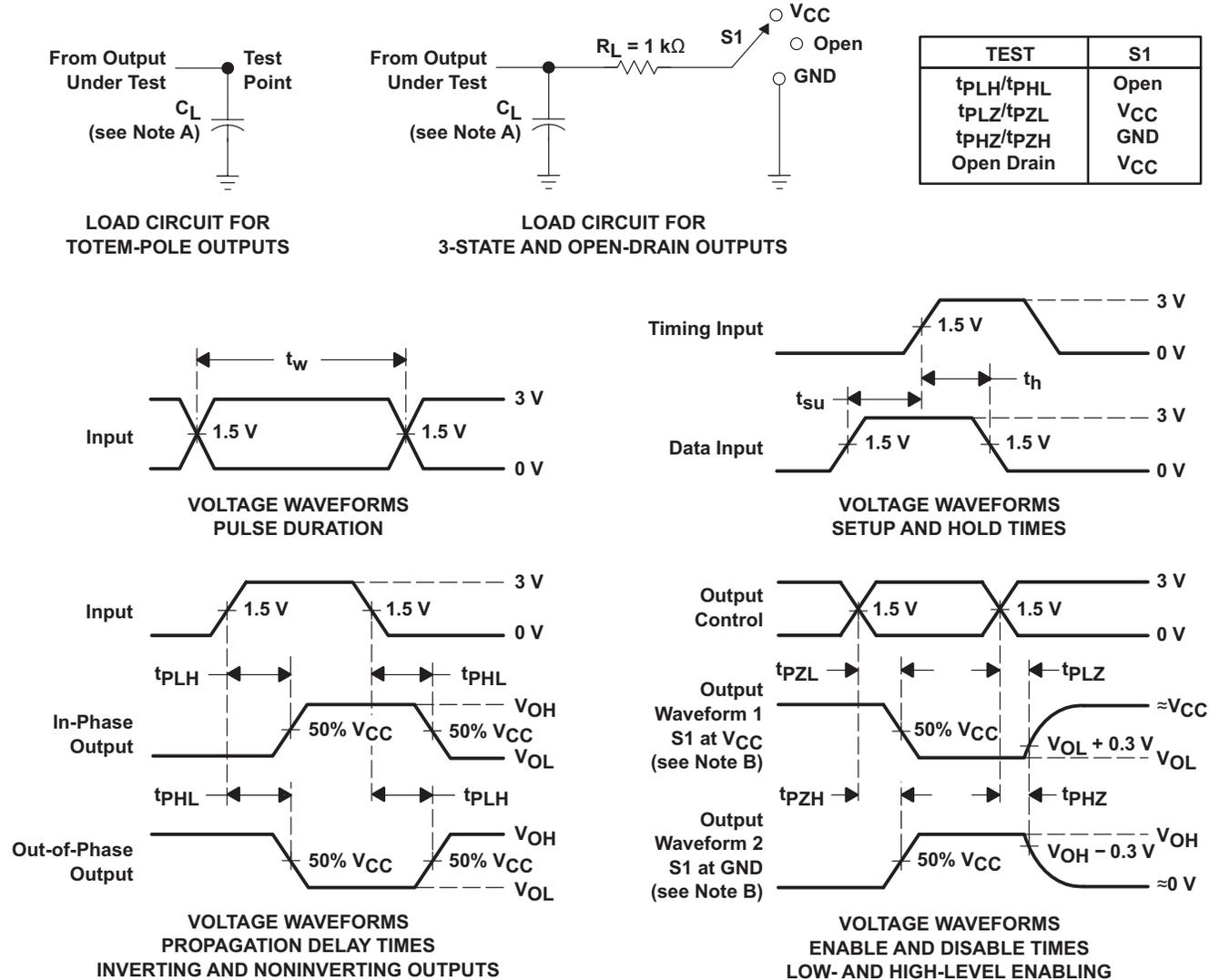
### 5.8 Typical Characteristics



**Figure 5-1. TPD vs Temperature**

## 6 Parameter Measurement Information

### 6.1



- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 3\text{ ns}$ ,  $t_f \leq 3\text{ ns}$ .
  - D. The outputs are measured one at a time, with one input transition per measurement.
  - E. All parameters and waveforms are not applicable to all devices.

Figure 6-1. Load Circuit and Voltage Waveforms

## 7 Detailed Description

### 7.1 Overview

The SN74AHCT1G32 device is a single 2-input positive-OR gate. The device performs the Boolean function  $Y = A + B$  or  $Y = \overline{\overline{A} \cdot \overline{B}}$  in positive logic.

The device has TTL inputs that allow up translation from 3.3 V to 5 V. The inputs are high impedance when  $V_{CC} = 0$  V.

### 7.2 Functional Block Diagram



Figure 7-1. Logic Diagram (Positive Logic)

### 7.3 Feature Description

- Slow rise and fall time on outputs allow for low noise outputs.
- TTL inputs
  - Allows up translation from 3.3 V to 5 V

### 7.4 Device Functional Modes

Table 7-1. Function Table

INPUTS <sup>(1)</sup>		OUTPUT <sup>(2)</sup>
A	B	Y
H	X	H
X	H	H
L	L	L

- (1) H = High Voltage Level, L = Low Voltage Level, X = Don't Care
- (2) H = Driving High, L = Driving Low, Z = High Impedance State

## 8 Application and Implementation

### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

### 8.1 Application Information

SN74AHCT1G32 is a low-drive CMOS device that can be used for a multitude of bus interface type applications where output ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs. The TTL inputs can accept voltages down to 3.3 V and translate up to 5 V.

### 8.2 Typical Application

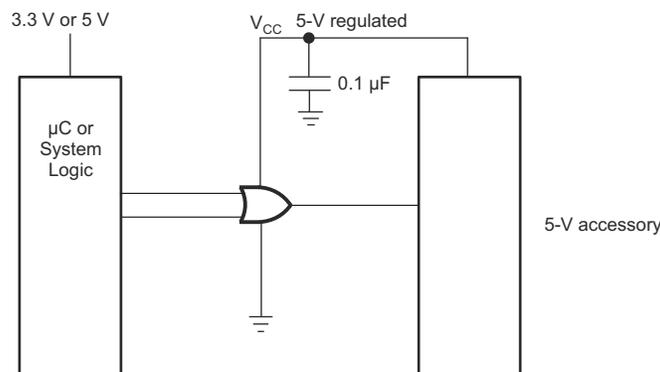


Figure 8-1. Typical Application Schematic

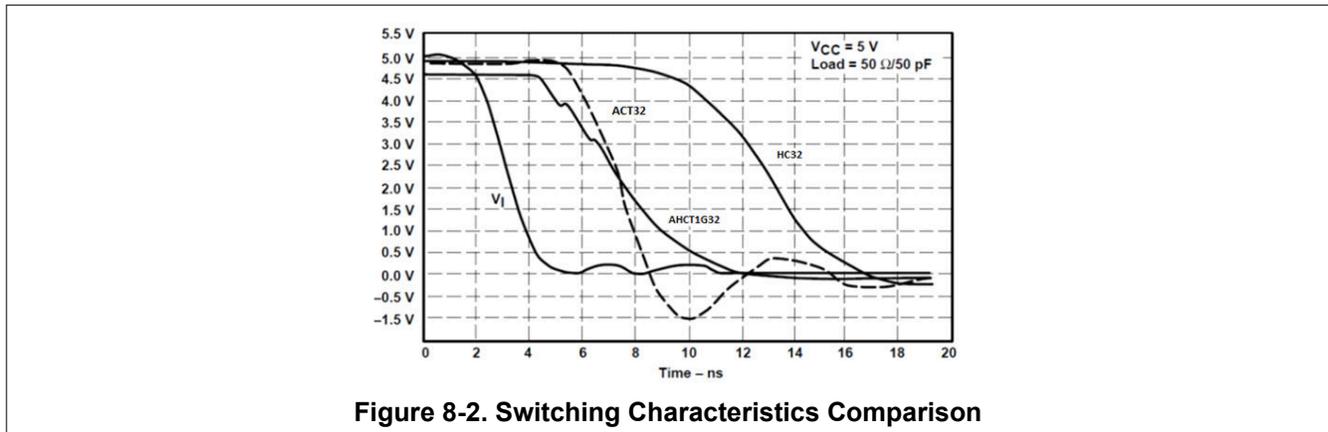
#### 8.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads, so routing and load conditions should be considered to prevent ringing.

#### 8.2.2 Detailed Design Procedure

- Recommended Input Conditions
  - For rise time and fall time specifications, see  $\Delta t/\Delta V$  in the [Section 5.3](#) table.
  - For specified High and low levels, see  $V_{IH}$  and  $V_{IL}$  in the [Section 5.3](#) table.
- Recommend Output Conditions
  - Load currents should not exceed 25 mA per output and 50 mA total for the part.
  - Outputs should not be pulled above  $V_{CC}$ .

## 8.2.3 Application Curves



## 8.3 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the [Section 5.3](#) table.

Each  $V_{CC}$  pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1  $\mu\text{F}$  is recommended. If there are multiple  $V_{CC}$  pins, 0.01  $\mu\text{F}$  or 0.022  $\mu\text{F}$  is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1  $\mu\text{F}$  and 1  $\mu\text{F}$  are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

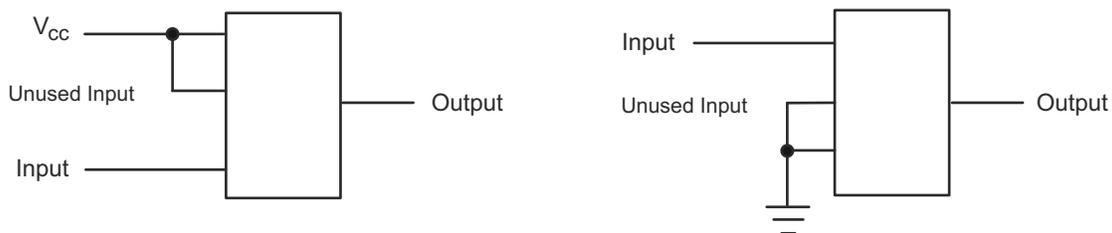
## 8.4 Layout

### 8.4.1 Layout Guidelines

When using multiple bit logic devices, inputs should not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input AND gate are used, or when only 3 of the 4-buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states.

Specified in [Figure 8-3](#) are rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or  $V_{CC}$ , whichever makes more sense or is more convenient. It is acceptable to float outputs unless the part is a transceiver. If the transceiver has an output enable pin, it will disable the outputs section of the part when asserted. This will not disable the input section of the I/Os so they also cannot float when disabled.

### 8.4.2 Layout Example



**Figure 8-3. Layout Diagram**

## 9 Device and Documentation Support

### 9.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](http://ti.com). Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 9.2 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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### 9.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.  
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### 9.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 9.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 10 Revision History

<b>Changes from Revision O (December 2014) to Revision P (March 2024)</b>	<b>Page</b>
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Updated thermal values for DBV package from RθJA = 231.3 to 278, RθJC(top) = 119.9 to 180.5, RθJB = 60.6 to 184.4, ΨJT = 17.8 to 115.4, ΨJB = 60.1 to 183.4, RθJC(bot) = N/A, all values in °C/W.....	5

<b>Changes from Revision N (June 2005) to Revision O (December 2014)</b>	<b>Page</b>
• Added <i>Applications</i> , <i>Device Information</i> table, <i>Pin Functions</i> table, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Typical Characteristics</i> , <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section.....	1
• Deleted <i>Ordering Information</i> table.....	1
• Changed MAX operating temperature to 125°C in <i>Recommended Operating Conditions</i> table. ....	4

## 11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">74AHCT1G32DBVRG4</a>	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(3CCF, B32G)
74AHCT1G32DBVRG4.A	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(3CCF, B32G)
<a href="#">74AHCT1G32DCKRG4</a>	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	BG3
74AHCT1G32DCKRG4.A	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	BG3
<a href="#">SN74AHCT1G32DBVR</a>	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	(36FH, 3CBF, B323, B32G, B32J, B32L, B32S)
SN74AHCT1G32DBVR.A	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	(36FH, 3CBF, B323, B32G, B32J, B32L, B32S)
<a href="#">SN74AHCT1G32DCK3</a>	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	SNBI	Level-1-260C-UNLIM	-40 to 85	BGY
SN74AHCT1G32DCK3.A	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	SNBI	Level-1-260C-UNLIM	-40 to 85	BGY
<a href="#">SN74AHCT1G32DCKR</a>	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	(1QU, BG3, BGG, BGJ, BGL, BGS)
SN74AHCT1G32DCKR.A	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	(1QU, BG3, BGG, BGJ, BGL, BGS)
<a href="#">SN74AHCT1G32DCKT</a>	Obsolete	Production	SC70 (DCK)   5	-	-	Call TI	Call TI	-40 to 125	(BG3, BGG, BGJ, BGS)
<a href="#">SN74AHCT1G32DRLR</a>	Active	Production	SOT-5X3 (DRL)   5	4000   LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	BGS
SN74AHCT1G32DRLR.A	Active	Production	SOT-5X3 (DRL)   5	4000   LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	BGS

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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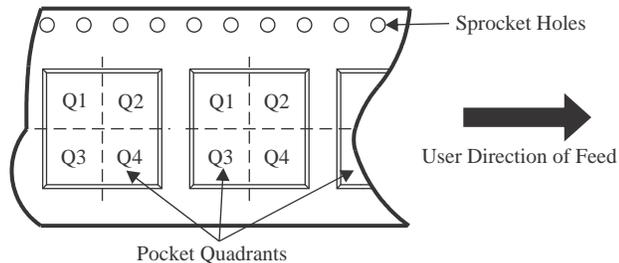
**OTHER QUALIFIED VERSIONS OF SN74AHCT1G32 :**

- Automotive : [SN74AHCT1G32-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74AHCT1G32DBVRG4	SOT-23	DBV	5	3000	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
74AHCT1G32DCKRG4	SC70	DCK	5	3000	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
SN74AHCT1G32DBVR	SOT-23	DBV	5	3000	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
SN74AHCT1G32DCKR	SC70	DCK	5	3000	180.0	8.4	2.3	2.5	1.2	4.0	8.0	Q3
SN74AHCT1G32DRLR	SOT-5X3	DRL	5	4000	180.0	8.4	1.98	1.78	0.69	4.0	8.0	Q3

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74AHCT1G32DBVRG4	SOT-23	DBV	5	3000	210.0	185.0	35.0
74AHCT1G32DCKRG4	SC70	DCK	5	3000	180.0	180.0	18.0
SN74AHCT1G32DBVR	SOT-23	DBV	5	3000	210.0	185.0	35.0
SN74AHCT1G32DCKR	SC70	DCK	5	3000	210.0	185.0	35.0
SN74AHCT1G32DRLR	SOT-5X3	DRL	5	4000	202.0	201.0	28.0

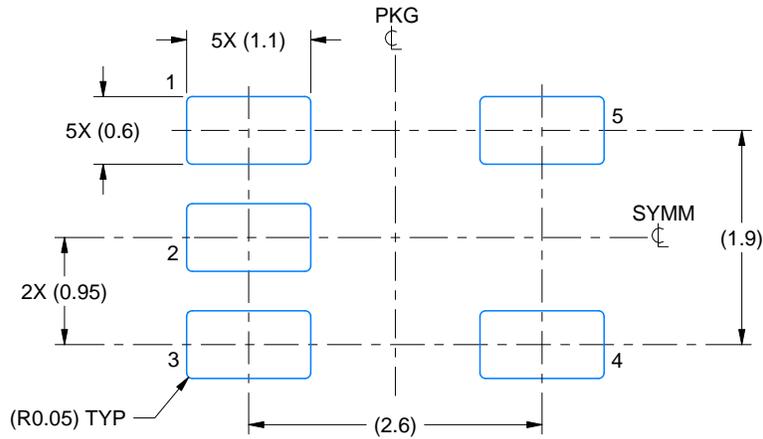


# EXAMPLE BOARD LAYOUT

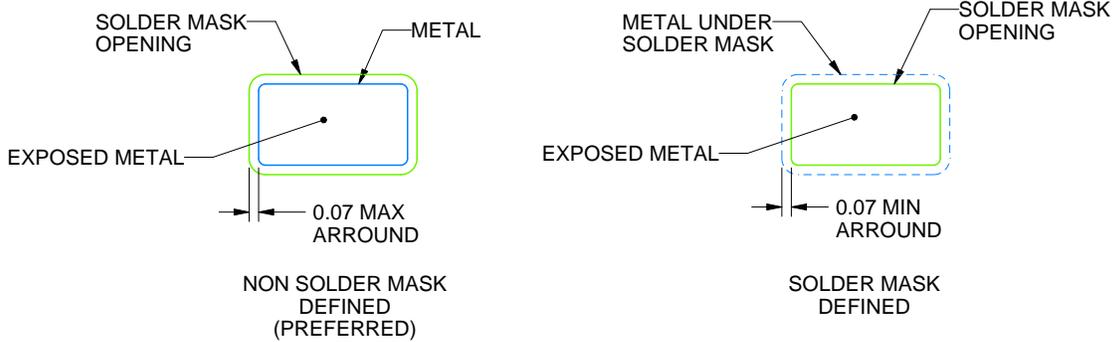
DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:15X



SOLDER MASK DETAILS

4214839/K 08/2024

NOTES: (continued)

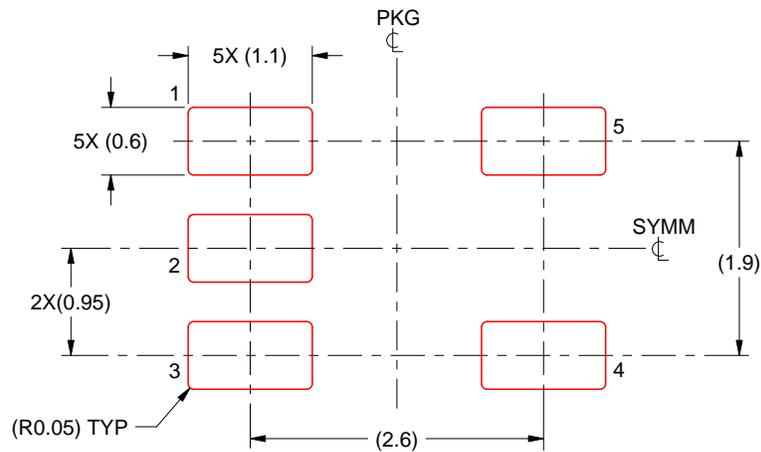
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR

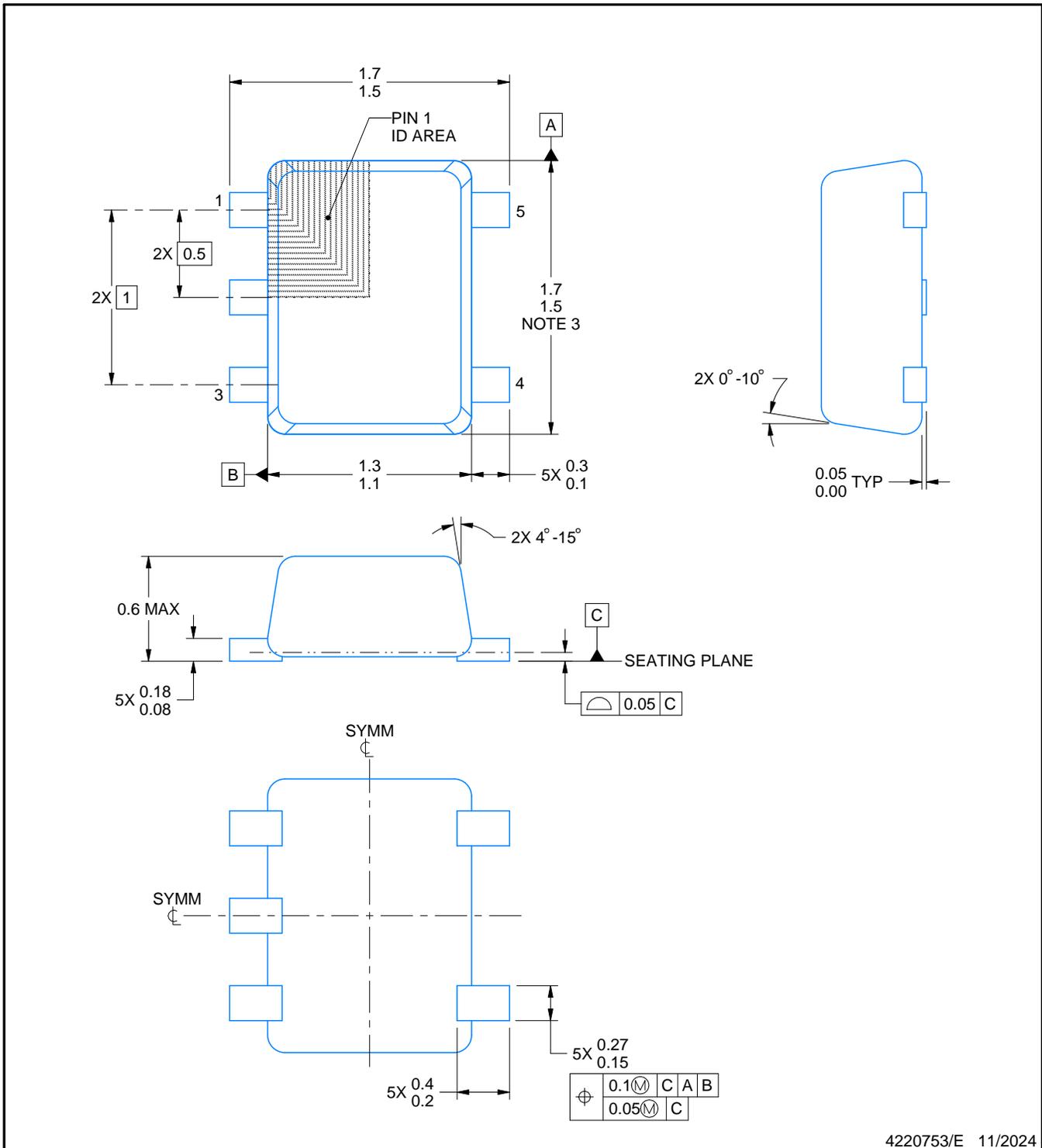
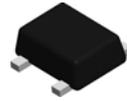


SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:15X

4214839/K 08/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



4220753/E 11/2024

NOTES:

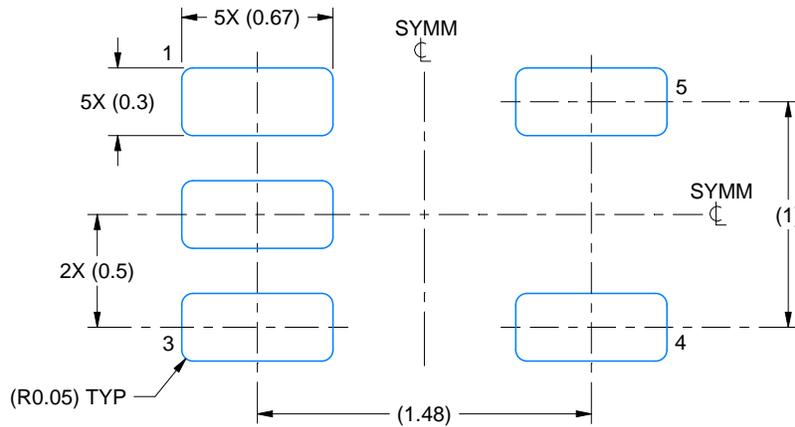
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-293 Variation UAAD-1

# EXAMPLE BOARD LAYOUT

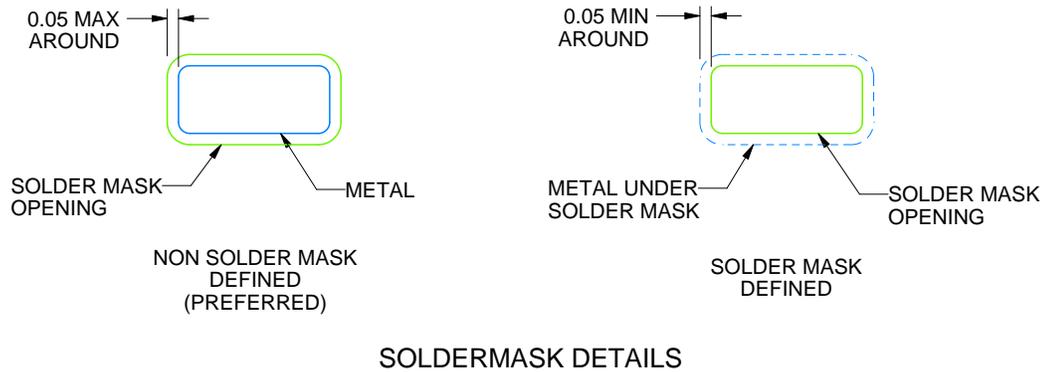
DRL0005A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



LAND PATTERN EXAMPLE  
SCALE:30X



SOLDERMASK DETAILS

4220753/E 11/2024

NOTES: (continued)

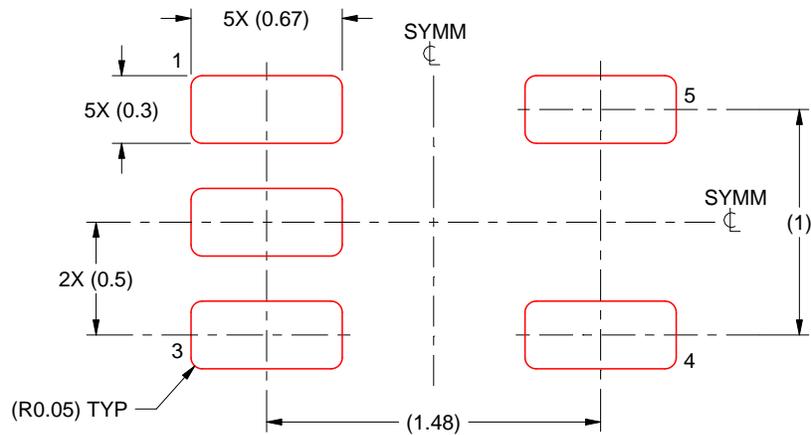
- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DRL0005A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICK STENCIL  
SCALE:30X

4220753/E 11/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

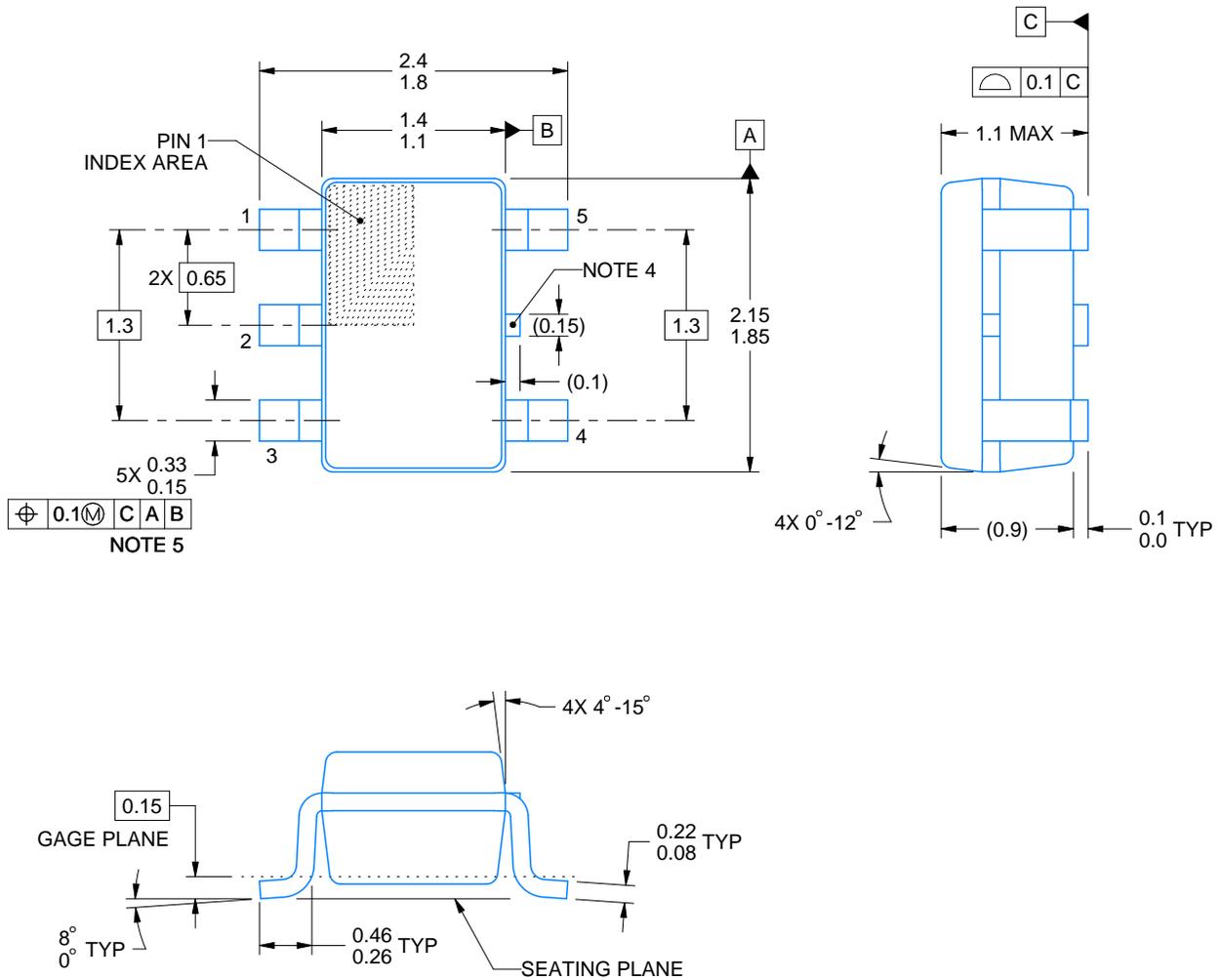
# DCK0005A



# PACKAGE OUTLINE

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



4214834/G 11/2024

**NOTES:**

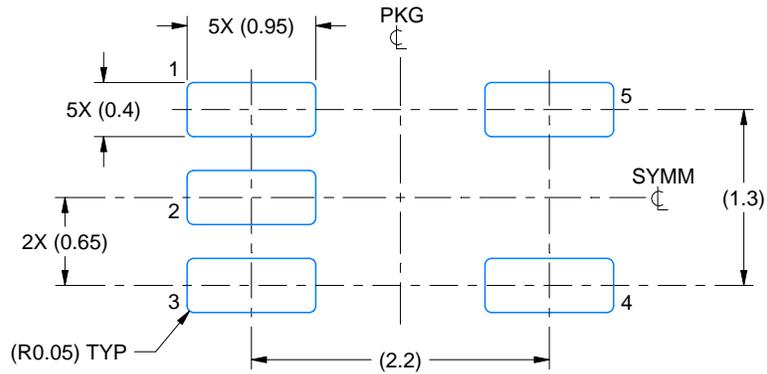
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-203.
4. Support pin may differ or may not be present.
5. Lead width does not comply with JEDEC.
6. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side

# EXAMPLE BOARD LAYOUT

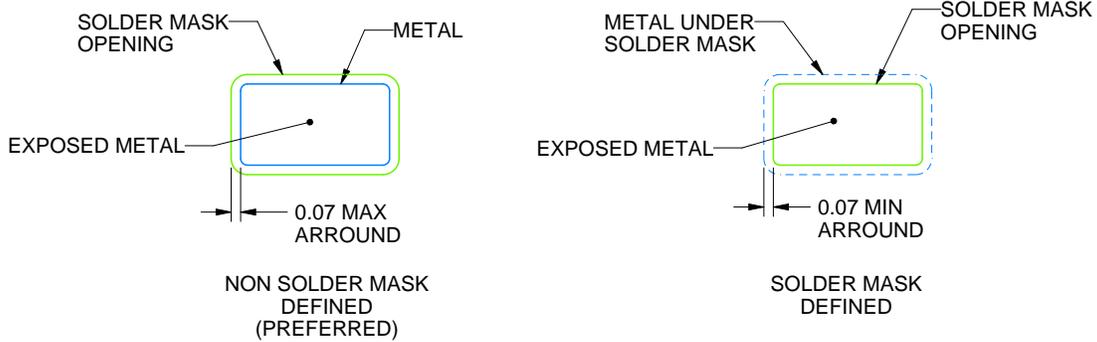
DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:18X



SOLDER MASK DETAILS

4214834/G 11/2024

NOTES: (continued)

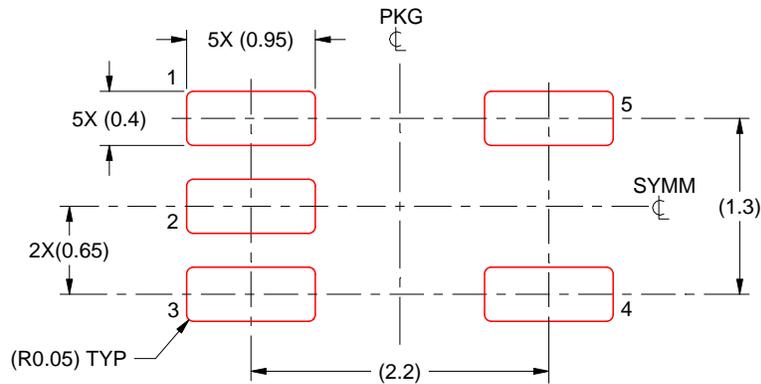
- 7. Publication IPC-7351 may have alternate designs.
- 8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 THICK STENCIL  
SCALE:18X

4214834/G 11/2024

NOTES: (continued)

9. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
10. Board assembly site may have different recommendations for stencil design.

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